MARKED UP VERSION OF CLAIMS WITH MARKING TO SHOW CHANGES MADE

Claim 1. (Previously Presented) A cleaning device comprising a shaped body made of porous polyvinyl acetal material having a uniform pore size throughout the material with over 90% of the pores ranging from about 7 microns to about 40 microns in size.

Claim 2. (Original) A cleaning device as claimed in claim 1 wherein said device is a roller having a smooth outer surface.

Claim 3. (Original) A cleaning device as claimed in claim 1 wherein said device is a pad.

Claim 4. (Original) A cleaning device as claimed in claim 1 wherein said device is a disk.

Claim 5. (Original) A cleaning device as claimed in claim 1 wherein said polyvinyl acetal material has an average pore size of about 20 microns.

Claim 6. (Previously Presented) A cleaning device as claimed in claim 1 wherein said material has about 95% of its pores with a size below 40 microns.

Claim 7. (Previously Presented) A cleaning device comprising a body made of porous polyvinyl acetal material, said polyvinyl acetal material having a bubble point pressure of about 0.92 PSI.

Claim 8. (Original) A cleaning device as claimed in claim 2 wherein said roller has an outside diameter of about 60mm and an inside diameter of about 30mm with a thickness of about 15mm.

Claim 9. (Original) A cleaning device as claimed in claim 1 wherein said material has a mean flow pore pressure of about 0.33 PSI.

Claim 10 (Currently Amended) A semiconductor cleaning device comprising a body made of porous polyvinyl acetal material with a cylindrical roller shape and a smooth outer surface, said material having uniform ~~gaseous~~ formed pore sizes throughout with at least 90% of the pores ranging from about 7 microns to about 40 microns in size with a fluid flow through rate which does not distort the roller during the cleaning process when fluid is passed through it to clean the same.

Claim 11. (Original) A semiconductor cleaning device as claimed in claim 10 wherein said polyvinyl acetal material has an average pore size of about 20 microns.

Claim 12. (Previously Presented) A semiconductor cleaning device as claimed in claim

10 wherein said material has 95% of its pores with a size below 40 microns.

Claim 13. (Currently Amended) A semiconductor cleaning device comprising a body made of porous polyvinyl acetal material with [[gas]] formed pores and having at least 95% of its pores with a size under 40 microns.

Claim 14. (Original) A semiconductor cleaning device as claimed in claim 10 wherein said roller is substantially skinless.

Claim 15. (Original) A semiconductor cleaning device as claimed in claim 10 wherein said material has a mean flow pore pressure of about 0.33 PSI.

Claim 16. (Previously Presented) A semiconductor cleaning device comprising a body made of porous polyvinyl acetal material having a uniform pore size throughout the material with at least 95% of the pores being less than 40 microns in size, said material having a mean flow pore size of about 20 microns.

Claim 17. (Original) A semiconductor cleaning device as claimed in claim 16 wherein said material has a mean flow pressure of about 0.33PSI.

Claim 18. (Previously Presented) A semiconductor cleaning device comprising a substantially cylindrical roller body made of polyvinyl acetal with a smooth outer surface and uniform material porosity having a mean flow pore pressure of about 0.30 PSI with 90% of its pores ranging from 7 to 40 microns in size and wet flow rate using water as a medium ranging from about 7.0 L/min to 80.0 L/min, said pores forming substantially empty cavities.

Claim 19. (Original) A semiconductor cleaning device as claimed in claim 18 wherein cleaning solvent flow through said roller ranges from 120 - 180 ml/minute.

Claim 20. (Previously Presented) A semiconductor cleaning device comprising a substantially cylindrical roller body made of polyvinyl acetal with a smooth outer surface and uniform material porosity having a mean flow pore pressure of about 0.30 PSI with 90% of its pores ranging from 7 to 40 microns in size and a dry flow rate ranging from about 25.0 L/min to 95.0 L/min, said pores forming substantially empty cavities.

Claim 21. (Previously Presented) A semiconductor cleaning device as claimed in claim 18 wherein said roller body polyvinyl acetal material has less than 0.1 ppm formaldehyde.

Claim 22. (Previously Presented) A cleaning device as claimed in claim 1 wherein said device is a roller.